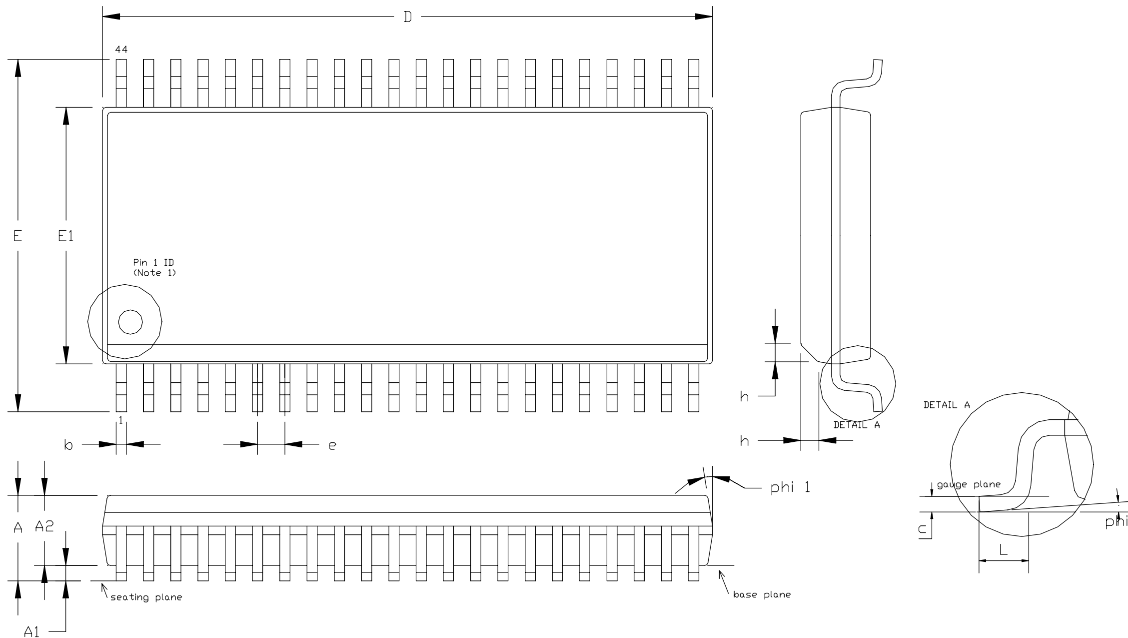
Date: 07.02.2013	**PACKAGE OUTLINE SPECIFICATION**	elmos Services BV
Author: ASto	44 Lead Small Outline Package (300mil) (QSOP44)	QM-No.: 08SP0691.05

Package Outline and Dimensions: No special JEDEC specification available for 300mil QSOP. Package dimensions are according JEDEC MS-013-E, variant AE (SO28). Differences are e (pitch) and b (terminal lead width, is within JEDEC MS-013-E but, in general, more at the lower limit).



Description	Symbol	mm			inch		
		min	**typ**	**max**	**min**	**typ**	**max**
Package height	A	--	--	2.65	--	--	0.104
Stand off	A1	0.10	--	0.30	0.004	--	0.012
Package body thickness	A2	2.05	--	--	0.081	--	--
Width of terminal leads, inclusive lead finish	b	0.31	--	0.51	0.012	--	0.020
Thickness of terminal leads, inclusive lead finish	c	0.20	--	0.33	0.008	--	0.013
Package length	D	17.90 BSC			0.705 BSC		
Package width	E	10.30 BSC			0.406 BSC		
Package body width	E1	7.50 BSC			0.295 BSC		
Lead pitch	e	0.80 BSC			0.031 BSC		
Length of terminal for soldering to substrate	L	0.4	--	1.27	0.016	--	0.050
body chamfer (45°)	h	0.25	--	0.75	0.010	--	0.030
Angle of lead mounting area	phi [°]	0	--	8	0	--	8
mold release angle	phi1 [°]	5	--	15	5	--	15
Number of terminal positions	N	44			44		

Note: the mm values are valid, the inch values contains rounding errors
Note 1: for assembler specific pin1 identification please see QM-document 08SP0363.xx (Pin 1 Specification)